

TIBPAL20L8-5C, TIBPAL20R4-5C, TIBPAL20R6-5C, TIBPAL20R8-5C
TIBPAL20L8-7M, TIBPAL20R4-7M, TIBPAL20R6-7M, TIBPAL20R8-7M
HIGH-PERFORMANCE *IMPACT-X*TM PAL[®] CIRCUITS

SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

- **High-Performance Operation:**
 - f_{max} (no feedback)
 - TIBPAL20R' -5C Series . . . 125 MHz Min
 - TIBPAL20R' -7M Series . . . 100 MHz Min
 - f_{max} (internal feedback)
 - TIBPAL20R' -5C Series . . . 125 MHz Min
 - TIBPAL20R' -7M Series . . . 100 MHz Min
 - f_{max} (external feedback)
 - TIBPAL20R' -5C Series . . . 117 MHz Min
 - TIBPAL20R' -7M Series . . . 74 MHz Min
 - Propagation Delay**
 - TIBPAL20L8-5C Series . . . 5 ns Max
 - TIBPAL20L8-7M Series . . . 7 ns Max
 - TIBPAL20R' -5C Series (CLK-to-Q) . . . 4 ns Max
 - TIBPAL20R' -7M Series (CLK-to-Q) . . . 6.5 ns Max

- **Functionally Equivalent, but Faster Than, Existing 24-Pin PLDs**
- **Preload Capability on Output Registers Simplifies Testing**
- **Power-Up Clear on Registered Devices (All Register Outputs are Set Low, but Voltage Levels at the Output Pins Go High)**
- **Package Options Include Both Plastic and Ceramic Chip Carriers in Addition to Plastic and Ceramic DIPs**
- **Security Fuse Prevents Duplication**

DEVICE	I INPUTS	3-STATE O OUTPUTS	REGISTERED Q OUTPUTS	I/O PORTS
PAL20L8	14	2	0	6
PAL20R4	12	0	4 (3-state buffers)	4
PAL20R6	12	0	6 (3-state buffers)	2
PAL20R8	12	0	8 (3-state buffers)	0

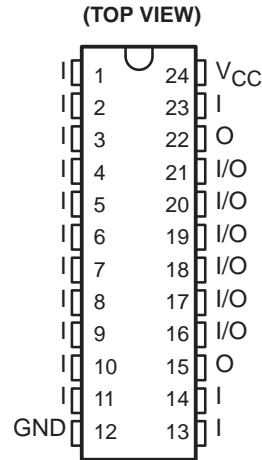
description

These programmable array logic devices feature high speed and functional equivalency when compared with currently available devices. These *IMPACT-X*TM circuits combine the latest Advanced Low-Power Schottky technology with proven titanium-tungsten fuses to provide reliable, high-performance substitutes for conventional TTL logic. Their easy programmability allows for quick design of custom functions and typically results in a more compact circuit board.

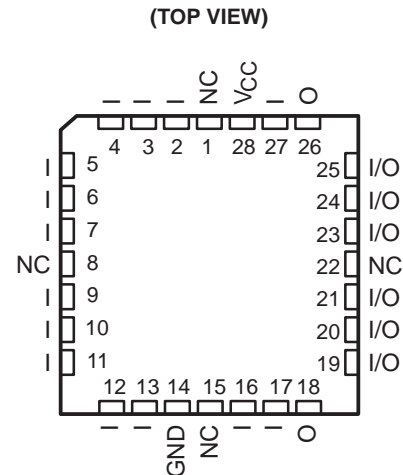
The TIBPAL20' C series is characterized from 0°C to 75°C. The TIBPAL20' M series is characterized for operation over the full military temperature range of -55°C to 125°C.

These devices are covered by U.S. Patent 4,410,987. *IMPACT-X* is a trademark of Texas Instruments Incorporated. PAL is a registered trademark of Advanced Micro Devices Inc.

TIBPAL20L8'
C SUFFIX . . . JT OR NT PACKAGE
M SUFFIX . . . JT PACKAGE



TIBPAL20L8'
C SUFFIX . . . FN PACKAGE
M SUFFIX . . . FK PACKAGE



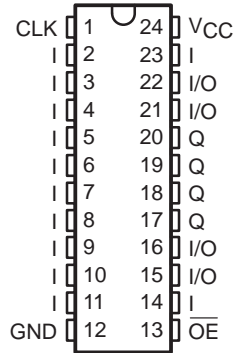
NC – No internal connection
 Pin assignments in operating mode

This document contains information on products in more than one phase of development. The status of each device is indicated on the page(s) specifying its electrical characteristics.

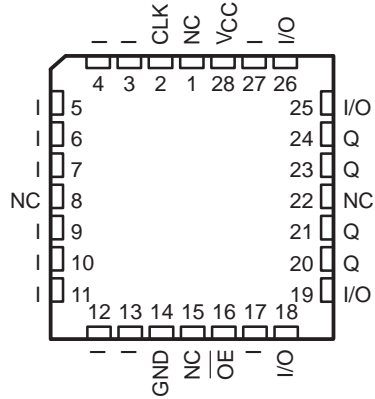


TIBPAL20R4-5C, TIBPAL20R6-5C, TIBPAL20R8-5C
TIBPAL20R4-7M, TIBPAL20R6-7M, TIBPAL20R8-7M
HIGH-PERFORMANCE *IMPACT-X*™ PAL® CIRCUITS
 SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

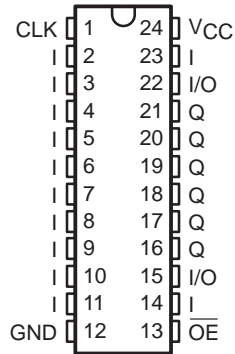
TIBPAL20R4'
C SUFFIX ... JT OR NT PACKAGE
M SUFFIX ... JT PACKAGE
(TOP VIEW)



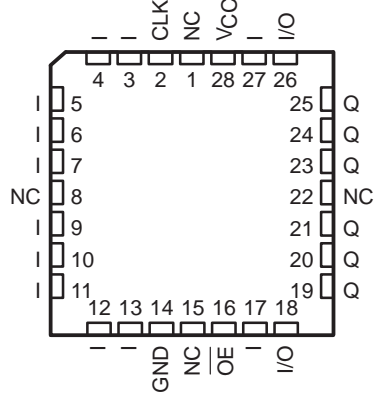
TIBPAL20R4'
C SUFFIX ... FN PACKAGE
M SUFFIX ... FK PACKAGE
(TOP VIEW)



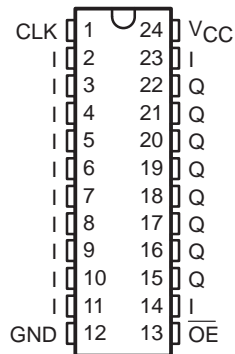
TIBPAL20R6'
C SUFFIX ... JT OR NT PACKAGE
M SUFFIX ... JT PACKAGE
(TOP VIEW)



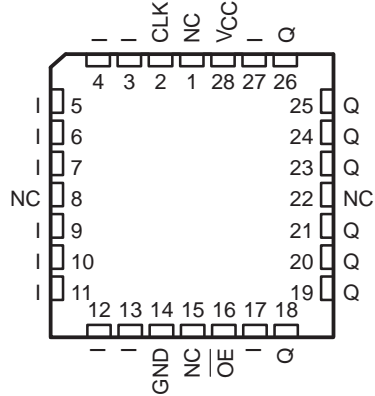
TIBPAL20R6'
C SUFFIX ... FN PACKAGE
M SUFFIX ... FK PACKAGE
(TOP VIEW)



TIBPAL20R8'
C SUFFIX ... JT OR NT PACKAGE
M SUFFIX ... JT PACKAGE
(TOP VIEW)



TIBPAL20R8'
C SUFFIX ... FN PACKAGE
M SUFFIX ... FK PACKAGE
(TOP VIEW)

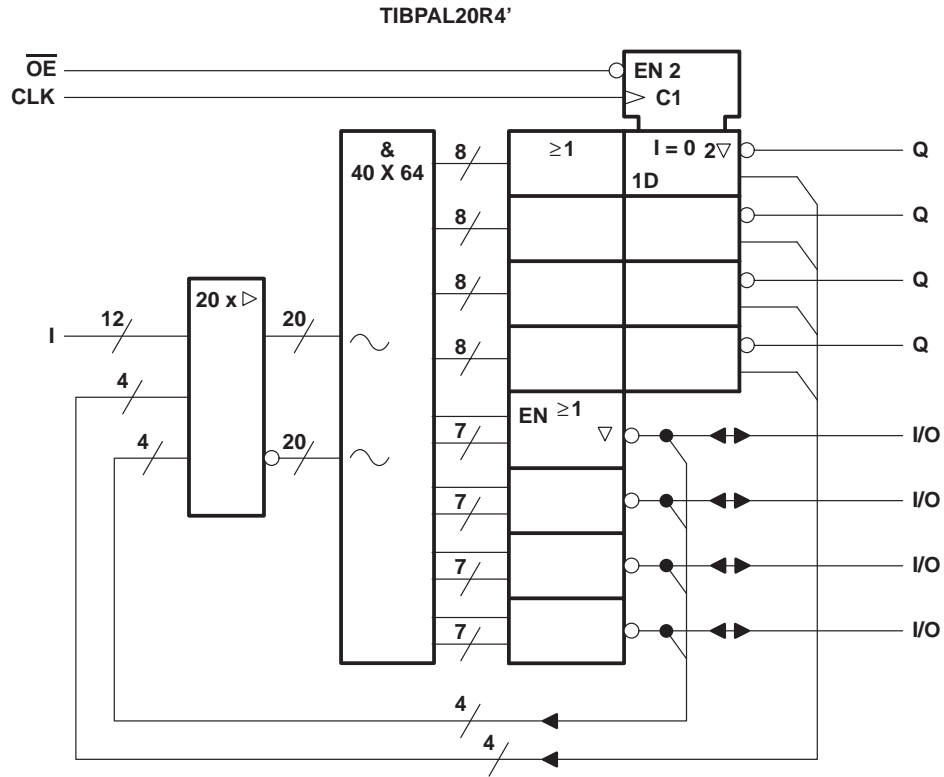
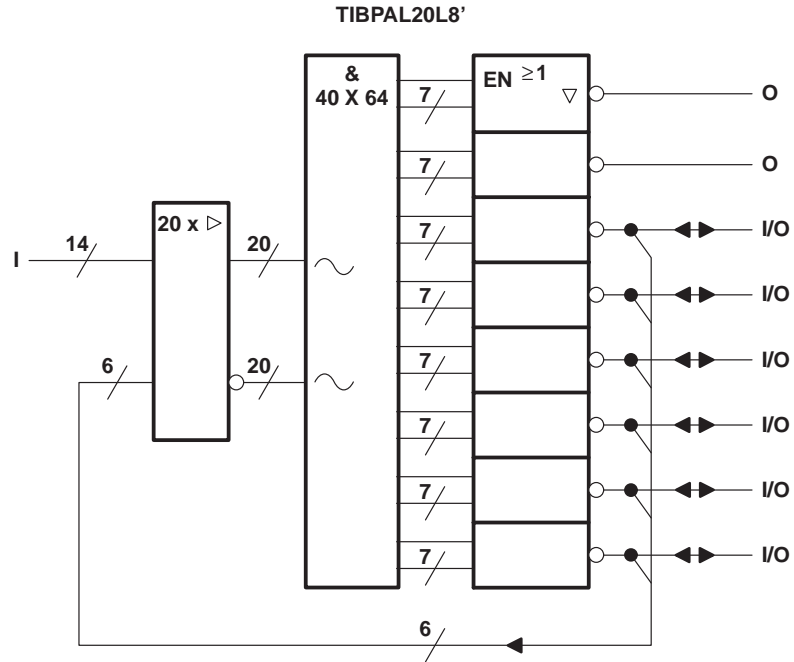


Pin assignments in operating mode

NC – No internal connection



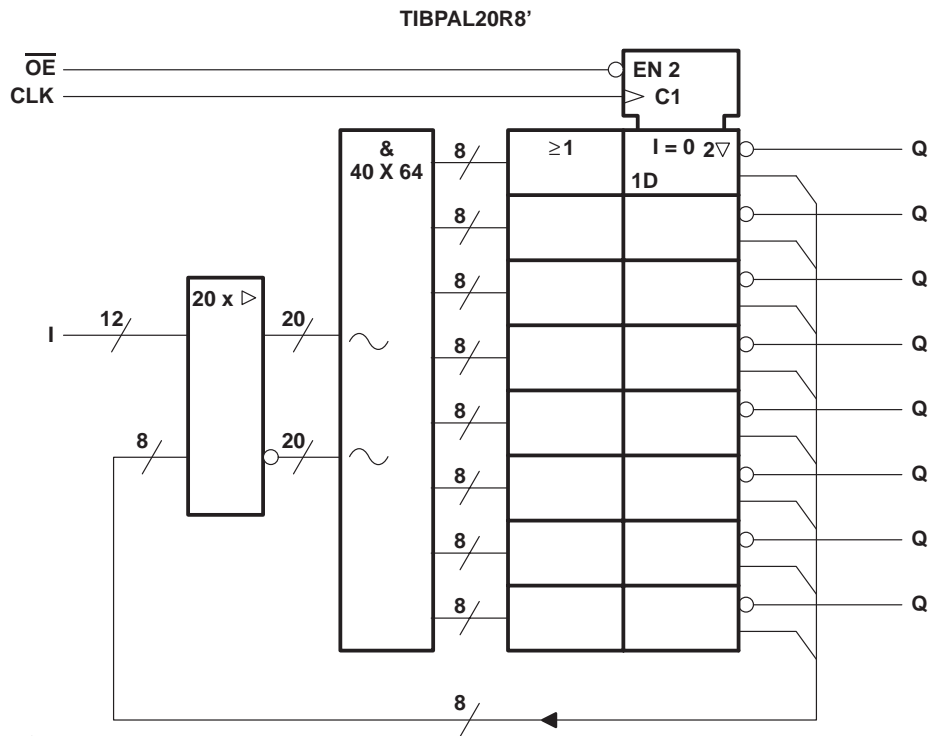
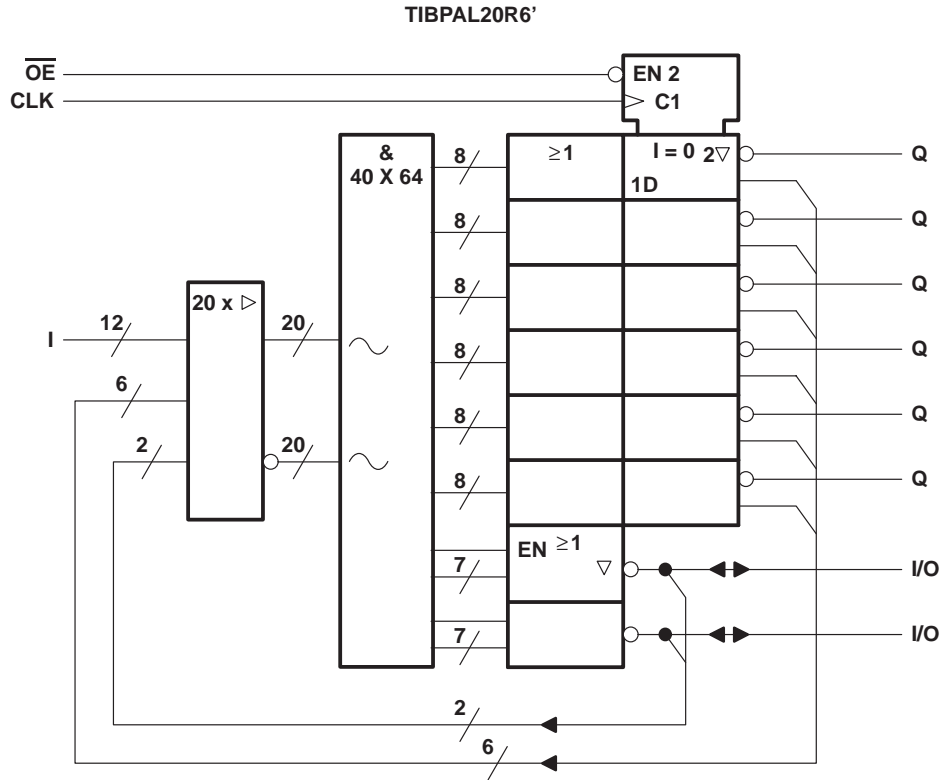
functional block diagrams (positive logic)



~ denotes fused inputs

TIBPAL20R6-5C, TIBPAL20R8-5C
 TIBPAL20R6-7M, TIBPAL20R8-7M
 HIGH-PERFORMANCE *IMPACT-X*™ PAL® CIRCUITS
 SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

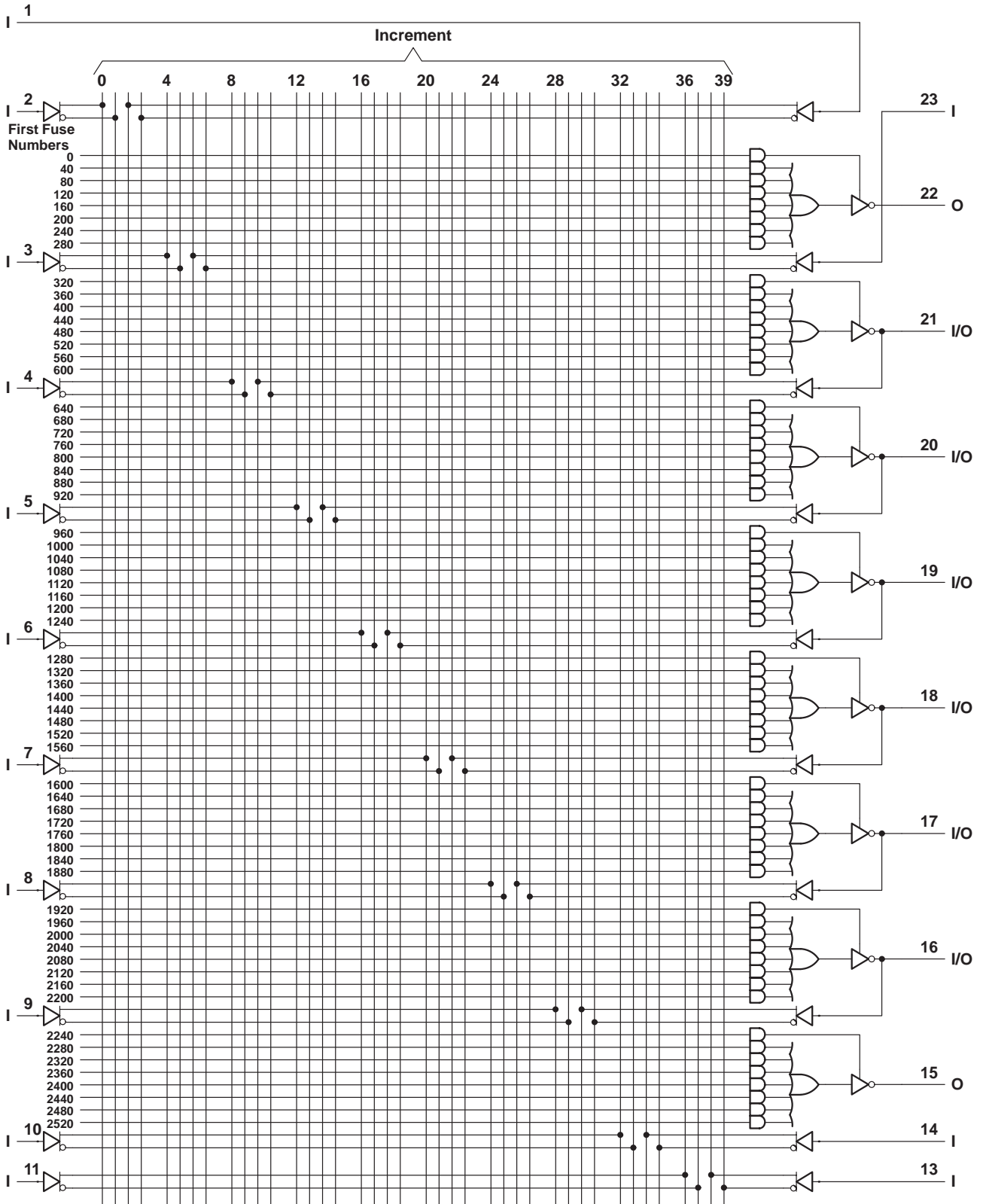
functional block diagrams (positive logic)



~ denotes fused inputs



logic diagram (positive logic)

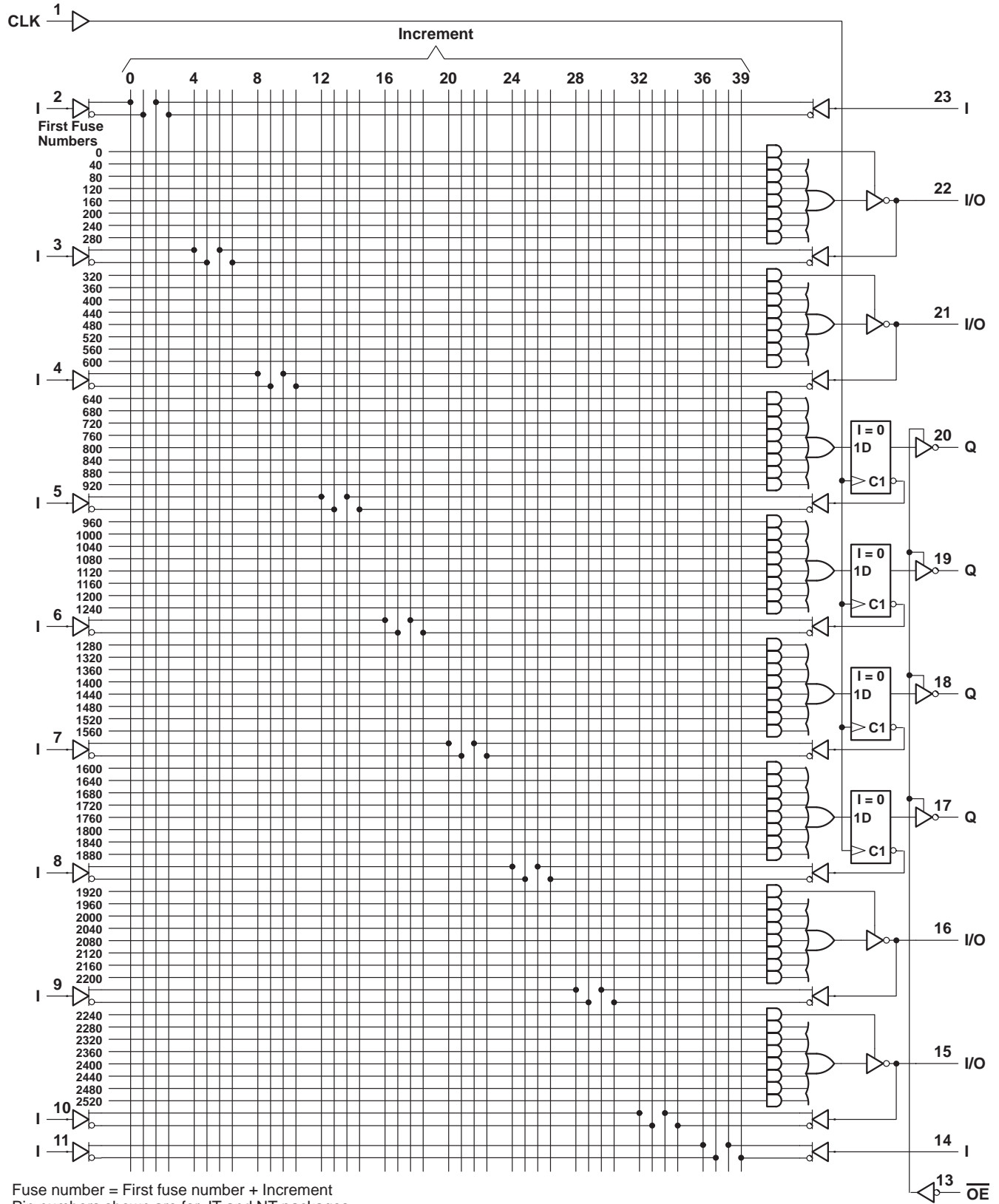


Fuse number = First fuse number + Increment
Pin numbers shown are for JT and NT packages.



TIBPAL20R4-5C
 TIBPAL20R4-7M
 HIGH-PERFORMANCE *IMPACT-X*™ PAL® CIRCUITS
 SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

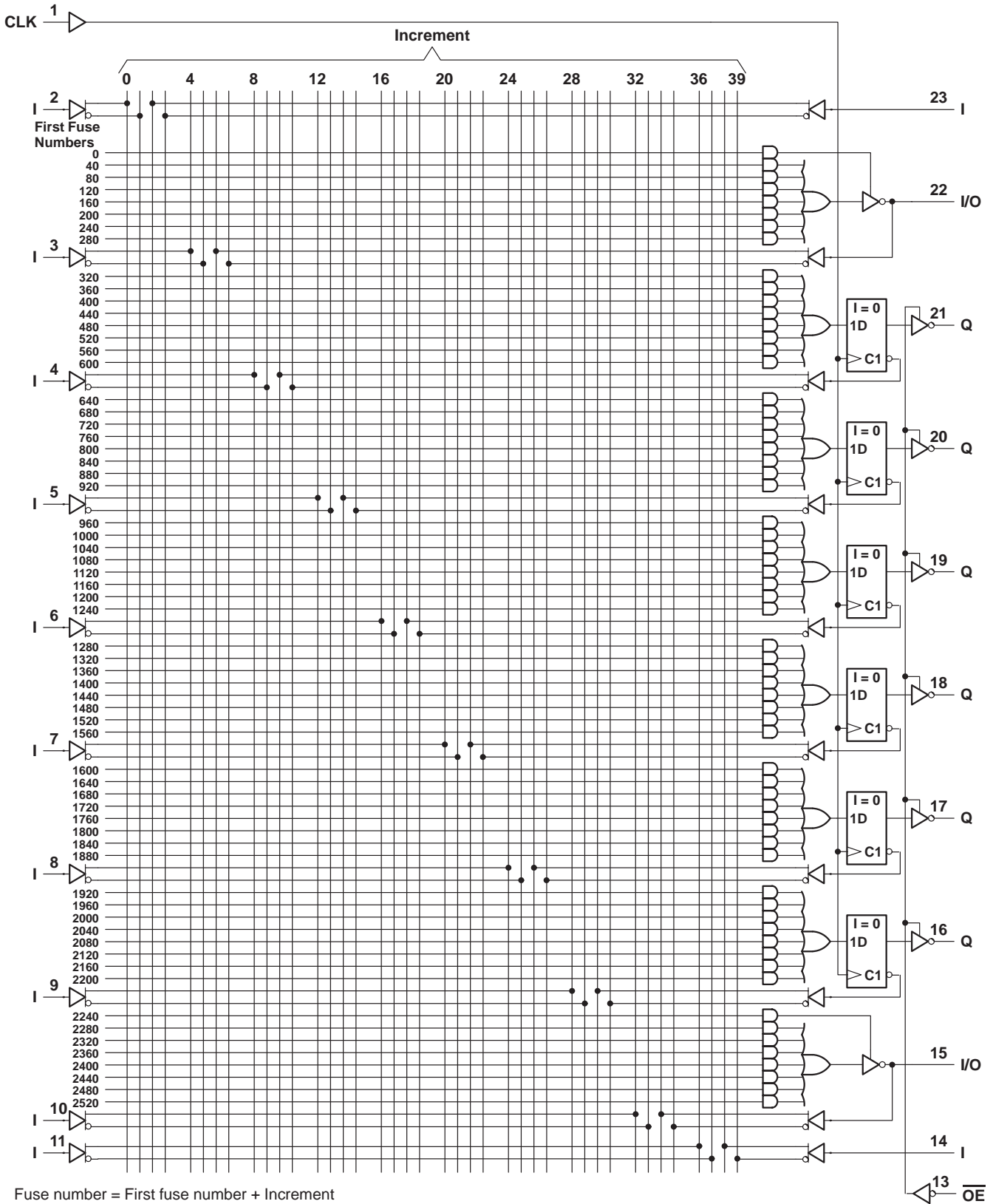
logic diagram (positive logic)



Fuse number = First fuse number + Increment
 Pin numbers shown are for JT and NT packages.



logic diagram (positive logic)

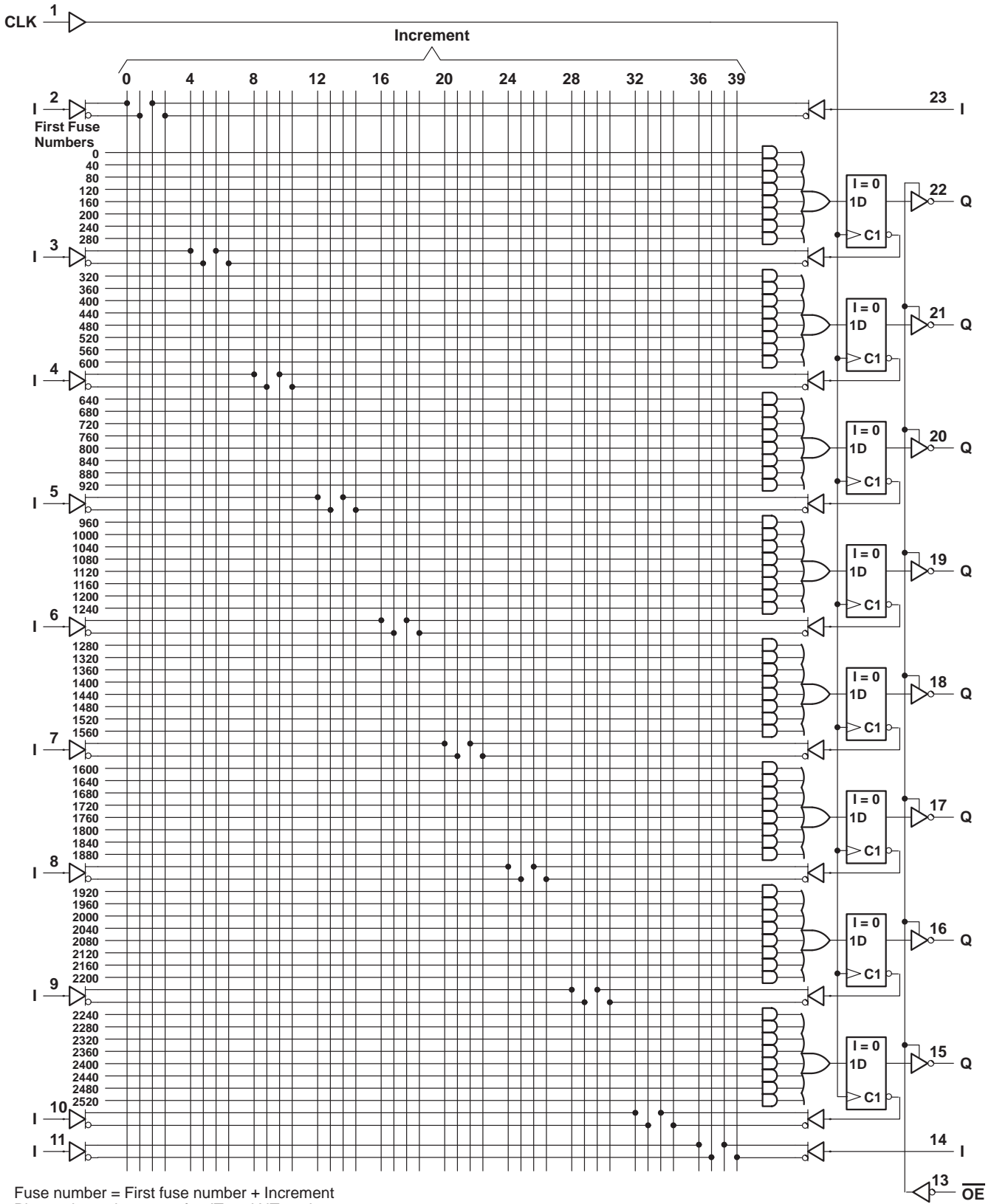


Fuse number = First fuse number + Increment
Pin numbers shown are for JT and NT packages.



TIBPAL20R8-5C
TIBPAL20R8-7M
HIGH-PERFORMANCE *IMPACT-X*™ PAL® CIRCUITS
 SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

logic diagram (positive logic)



Fuse number = First fuse number + Increment
 Pin numbers shown are for JT and NT packages.



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	0°C to 75°C
Storage temperature range	–65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.75	5	5.25	V
V_{IH}	High-level input voltage (see Note 2)	2		5.5	V
V_{IL}	Low-level input voltage (see Note 2)			0.8	V
I_{OH}	High-level output current			–3.2	mA
I_{OL}	Low-level output current			24	mA
T_A	Operating free-air temperature	0	25	75	°C

NOTE 2: These are absolute voltage levels with respect to the ground pin of the device and include all overshoots due to system and/or tester noise. Testing these parameters should not be attempted without suitable equipment.

electrical characteristics over recommended operating free-air temperature range

PARAMETER	TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}	$V_{CC} = 4.75$ V,	$I_I = -18$ mA		–0.8	–1.5	V
V_{OH}	$V_{CC} = 4.75$ V,	$I_{OH} = -3.2$ mA	2.4	2.7		V
V_{OL}	$V_{CC} = 4.75$ V,	$I_{OL} = 24$ mA		0.3	0.5	V
$I_{OZH}‡$	$V_{CC} = 5.25$ V,	$V_O = 2.7$ V			100	μA
$I_{OZL}‡$	$V_{CC} = 5.25$ V,	$V_O = 0.4$ V			–100	μA
I_I	$V_{CC} = 5.25$ V,	$V_I = 5.5$ V			100	μA
$I_{IH}‡$	$V_{CC} = 5.25$ V,	$V_I = 2.7$ V			25	μA
$I_{IL}‡$	$V_{CC} = 5.25$ V,	$V_I = 0.4$ V			–250	μA
$I_{OS}§$	$V_{CC} = 5.25$ V,	$V_O = 0.5$ V	–30	–70	–130	mA
I_{CC}	$V_{CC} = 5.25$ V,	$V_I = 0$, Outputs open			210	mA
C_i	$f = 1$ MHz,	$V_I = 2$ V		8.5		pF
C_o	$f = 1$ MHz,	$V_O = 2$ V		10		pF

† All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ\text{C}$.

‡ I/O leakage is the worst case of I_{OZL} and I_{IL} or I_{OZH} and I_{IH} , respectively.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. V_O is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	TIBPAL20L8-5CFN		TIBPAL20L8-5CJT TIBPAL20L8-5CNT		UNIT
				MIN	MAX	MIN	MAX	
t_{pd}	I, I/O	O, I/O with up to 4 outputs switching	R1 = 200 Ω, R2 = 200 Ω, See Figure 8	1.5	5	1.5	5	ns
	I, I/O	O, I/O with more than 4 outputs switching		1.5	5	1.5	5.5	
t_{en}	I, I/O	O, I/O		2	7	2	7	ns
t_{dis}	I, I/O	O, I/O		2	7	2	7	ns

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



TIBPAL20R4-5C, TIBPAL20R6-5C HIGH-PERFORMANCE *IMPACT-X*™ PAL® CIRCUITS

SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	0°C to 75°C
Storage temperature range	–65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.75	5	5.25	V
V_{IH}	High-level input voltage (see Note 2)	2		5.5	V
V_{IL}	Low-level input voltage (see Note 2)			0.8	V
I_{OH}	High-level output current			–3.2	mA
I_{OL}	Low-level output current			24	mA
f_{clock}	Clock frequency	0		125	MHz
t_w	Pulse duration, clock	High		4	ns
		Low		4	
t_{su}	Setup time, input or feedback before clock↑	4.5			ns
t_h	Hold time, input or feedback after clock↑	0			ns
T_A	Operating free-air temperature	0	25	75	°C

NOTE 2: These are absolute voltage levels with respect to the ground pin of the device and include all overshoots due to system and/or tester noise. Testing these parameters should not be attempted without suitable equipment.

TIBPAL20R4-5C, TIBPAL20R6-5C HIGH-PERFORMANCE *IMPACT-X*™ *PAL*® CIRCUITS

SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}		V _{CC} = 4.75 V,	I _I = -18 mA		-0.8	-1.5	V
V _{OH}		V _{CC} = 4.75 V,	I _{OH} = -3.2 mA	2.4	2.7		V
V _{OL}		V _{CC} = 4.75 V,	I _{OL} = 24 mA		0.3	0.5	V
I _{OZH} ‡		V _{CC} = 5.25 V,	V _O = 2.7 V			100	μA
I _{OZL} ‡		V _{CC} = 5.25 V,	V _O = 0.4 V			-100	μA
I _I		V _{CC} = 5.25 V,	V _I = 5.5 V			100	μA
I _{IH} ‡		V _{CC} = 5.25 V,	V _I = 2.7 V			25	μA
I _{IL} ‡		V _{CC} = 5.25 V,	V _I = 0.4 V			-250	μA
I _{OS} §		V _{CC} = 5.25 V,	V _O = 0.5 V	-30	-70	-130	mA
I _{CC}		V _{CC} = 5.25 V,	V _I = 0, Outputs open			210	mA
C _i	I	f = 1 MHz,	V _I = 2 V	8.5			pF
	CLK/OE			7.5			
C _o	I/O	f = 1 MHz,	V _O = 2 V	10			pF
	Q			7			

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	TIBPAL20R4-5CFN TIBPAL20R6-5CFN			TIBPAL20R4-5CJT TIBPAL20R4-5CNT TIBPAL20R6-5CJT TIBPAL20R6-5CNT			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
f _{max} ¶	without feedback		R1 = 200 Ω, R2 = 200 Ω, See Figure 8	125			125			MHz
	with internal feedback (counter configuration)			125			125			
	with external feedback			117			111			
t _{pd}	CLK↑	Q		1.5			4			ns
t _{pd}	CLK↑	Internal feedback					3.5			ns
t _{pd}	I, I/O	I/O		1.5			5			ns
t _{en}	\overline{OE} ↓	Q		1.5			6			ns
t _{dis}	\overline{OE} ↑	Q		1			6.5			ns
t _{en}	I, I/O	I/O		2			7			ns
t _{dis}	I, I/O	I/O		2			7			ns
t _r			1.5			1.5			ns	
t _f			1.5			1.5			ns	
t _{sk(o)} #	Skew between registered outputs		0.5			0.5			ns	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ I/O leakage is the worst case of I_{OZL} and I_{IL} or I_{OZH} and I_{IH}, respectively.

§ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. V_O is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

¶ See 'f_{max} Specification' near the end of this data sheet.

t_{sk(o)} is the skew time between registered outputs.

TIBPAL20R8-5C HIGH-PERFORMANCE *IMPACT-X*™ *PAL*® CIRCUITS

SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	0°C to 75°C
Storage temperature range	–65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.75	5	5.25	V
V_{IH}	High-level input voltage (see Note 2)	2		5.5	V
V_{IL}	Low-level input voltage (see Note 2)			0.8	V
I_{OH}	High-level output current			–3.2	mA
I_{OL}	Low-level output current			24	mA
f_{clock}	Clock frequency	0		125	MHz
t_w	Pulse duration, clock	High		4	ns
		Low		4	
t_{su}	Setup time, input or feedback before clock↑	4.5			ns
t_h	Hold time, input or feedback after clock↑	0			ns
T_A	Operating free-air temperature	0	25	75	°C

NOTE 2: These are absolute voltage levels with respect to the ground pin of the device and include all overshoots due to system and/or tester noise. Testing these parameters should not be attempted without suitable equipment.

electrical characteristics over recommended operating free-air temperature range

PARAMETER	TEST CONDITIONS	TIBPAL20R8-5CFN			TIBPAL20R8-5CJT TIBPAL20R8-5CNT			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}	V _{CC} = 4.75 V, I _I = -18 mA	-0.8	-1.5		-0.8	-1.5		V
V _{OH}	V _{CC} = 4.75 V, I _{OH} = -3.2 mA	2.4	2.7		2.4	2.7		V
V _{OL}	V _{CC} = 4.75 V, I _{OL} = 24 mA		0.3	0.5		0.3	0.5	V
I _{OZH}	V _{CC} = 5.25 V, V _O = 2.7 V			100			100	μA
I _{OZL}	V _{CC} = 5.25 V, V _O = 0.4 V			-100			-100	μA
I _I	V _{CC} = 5.25 V, V _I = 5.5 V			100			100	μA
I _{IH}	V _{CC} = 5.25 V, V _I = 2.7 V			25			25	μA
I _{IL}	V _{CC} = 5.25 V, V _I = 0.4 V			-250			-250	μA
I _{OS‡}	V _{CC} = 5.25 V, V _O = 0.5 V	-30	-70	-130	-30	-70	-130	mA
I _{CC}	V _{CC} = 5.25 V, V _I = 0, Outputs open			210			210	mA
C _i	f = 1 MHz, V _I = 2 V	I			6.5			pF
		CLK/OE			5.5			
C _o	f = 1 MHz, V _O = 2 V	10			8			pF

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	TIBPAL20R8-5CFN			TIBPAL20R8-5CJT TIBPAL20R8-5CNT			UNIT	
				MIN	TYP†	MAX	MIN	TYP†	MAX		
f _{max} §	without feedback		R1 = 200 Ω, R2 = 200 Ω, See Figure 8	125			125			MHz	
	with internal feedback (counter configuration)			125			125				
	with external feedback			117			111				
t _{pd}	CLK↑	Q		with up to 4 outputs switching	1.5			4			ns
	CLK↑	Q		with more than 4 outputs switching	1.5			4.5			
t _{pd} ¶	CLK↑	Internal feedback		3.5			3.5			ns	
t _{en}	OE↓	Q		1.5			6			ns	
t _{dis}	OE↑	Q		1			6.5			ns	
t _r					1.5			1.5			ns
t _f					1.5			1.5			ns
t _{sk(o)} #	Skew between outputs			0.5			0.5			ns	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. V_O is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

§ See 'f_{max} Specification' near the end of this data sheet.

¶ This parameter is calculated from the measured f_{max} with internal feedback in a counter configuration (see Figure 4 for illustration).

t_{sk(o)} is the skew time between registered outputs.

TIBPAL20L8-7M, TIBPAL20R4-7M, TIBPAL20R6-7M, TIBPAL20R8-7M HIGH-PERFORMANCE *IMPACT-X*™ *PAL*® CIRCUITS

SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	7 V
Input voltage (see Note 1)	5.5 V
Voltage applied to disabled output (see Note 1)	5.5 V
Operating free-air temperature range	–55°C to 125°C
Storage temperature range	–65°C to 150°C

NOTE 1: These ratings apply except for programming pins during a programming cycle or during a preload cycle.

recommended operating conditions

		MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage (see Note 2)	2		5.5	V
V_{IL}	Low-level input voltage (see Note 2)			0.8	V
I_{OH}	High-level output current			–2	mA
I_{OL}	Low-level output current			12	mA
f_{clock}^\dagger	Clock frequency	0		100	MHz
t_w^\dagger	Pulse duration, clock	High		5	ns
		Low		5	
t_{su}^\dagger	Setup time, input or feedback before clock \uparrow	7			ns
t_h^\dagger	Hold time, input or feedback after clock \uparrow	0			ns
T_A	Operating free-air temperature	–55	25	125	°C

$^\dagger f_{clock}$, t_w , t_{su} , and t_h do not apply to TIBPAL16L8'

NOTE 2: These are absolute voltage levels with respect to the ground pin of the device and include all overshoots due to system and/or tester noise. Testing these parameters should not be attempted without suitable equipment.

PRODUCT PREVIEW

PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

TIBPAL20L8-7M, TIBPAL20R4-7M, TIBPAL20R6-7M, TIBPAL20R8-7M HIGH-PERFORMANCE *IMPACT-X*TM PAL[®] CIRCUITS

SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

electrical characteristics over recommended operating free-air temperature range

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V _{IK}		V _{CC} = 4.5 V,	I _I = -18 mA		-0.8	-1.5	V
V _{OH}		V _{CC} = 4.5 V,	I _{OH} = -2 mA	2.4	2.7		V
V _{OL}		V _{CC} = 4.5 V,	I _{OL} = 12 mA		0.25	0.5	V
I _{OZH}	0, Q outputs	V _{CC} = 5.5 V,	V _O = 2.7 V			20	μA
	I/O ports					100	
I _{OZL}	0, Q outputs	V _{CC} = 5.5 V,	V _O = 0.4 V			-20	μA
	I/O ports					-250	
I _I		V _{CC} = 5.5 V,	V _I = 5.5 V			1	mA
I _{IH}	I/O ports	V _{CC} = 5.5 V,	V _I = 2.7 V			100	μA
	All others					25	
I _{IL}		V _{CC} = 5.5 V,	V _I = 0.4 V			-250	μA
I _{OS‡}		V _{CC} = 5.5 V,	V _O = 0.5 V	-30	-70	-130	mA
I _{CC}		V _{CC} = 5.5 V,	V _I = GND, $\overline{OE} = V_{IH}$, Outputs open			220	mA
C _i	I	f = 1 MHz,	V _I = 2 V			8.5	pF
	CLK/ \overline{OE}					7.5	
C _o		f = 1 MHz,	V _O = 2 V			10	pF

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second. V_O is set at 0.5 V to avoid test problems caused by test equipment ground degradation.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITION	MIN	MAX	UNIT
f _{max} §	without feedback		R1 = 390 Ω, R2 = 750 Ω, See Figure 8	100		MHz
	with internal feedback (counter configuration)			100		
	with external feedback			74		
t _{pd}	I, I/O	O, I/O		1	7	ns
t _{pd}	CLK	Q		1	7	ns
t _{en}	OE↓	Q		1	8	ns
t _{dis}	OE↑	Q	1	10	ns	
t _{en}	I, I/O	O, I/O	1	9	ns	
t _{dis}	I, I/O	O, I/O	1	10	ns	

§ See 'f_{max} Specification' near the end of this data sheet. f_{max} does not apply for TIBPAL20L8'. f_{max} with external feedback is not production tested and is calculated from the equation found in the f_{max} specifications section.

PRODUCT PREVIEW

programming information

Texas Instruments programmable logic devices can be programmed using widely available software and inexpensive device programmers.

Complete programming specifications, algorithms, and the latest information on hardware, software, and firmware are available upon request. Information on programmers capable of programming Texas Instruments programmable logic is also available, upon request, from the nearest TI field sales office, local authorized TI distributor, or by calling Texas Instruments at (214) 997-5666.

asynchronous preload procedure for registered outputs (see Figure 1 and Note 3)

The output registers can be preloaded to any desired state during device testing. This permits any state to be tested without having to step through the entire state-machine sequence. Each register is preloaded individually by following the steps given below.

- Step 1. With V_{CC} at 5 volts and Pin 1 at V_{IL} , raise Pin 13 to V_{IHH} .
- Step 2. Apply either V_{IL} or V_{IH} to the output corresponding to the register to be preloaded.
- Step 3. Lower Pin 13 to 5 V.
- Step 4. Remove output voltage, then lower Pin 13 to V_{IL} . Preload can be verified by observing the voltage level at the output pin.

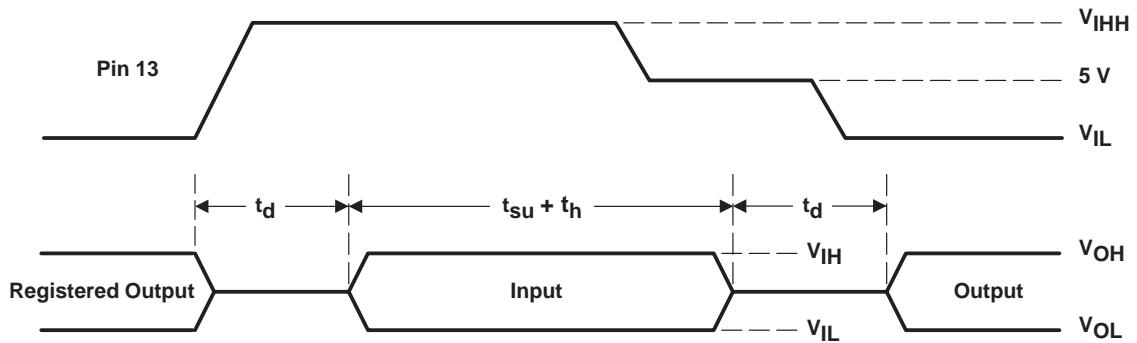
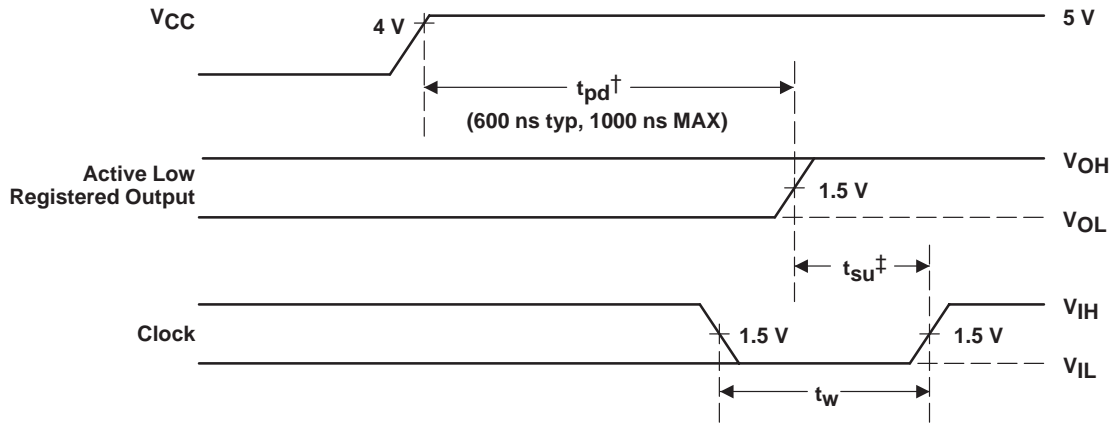


Figure 1. Asynchronous Preload Waveforms

NOTE 3: $t_d = t_{su} = t_h = 100$ ns to 1000 ns, $V_{IHH} = 10.25$ V to 10.75 V

power-up reset, see Figure 2

Following power up, all registers are reset to zero. This feature provides extra flexibility to the system designer and is especially valuable in simplifying state-machine initialization. To ensure a valid power-up reset, it is important that the rise of V_{CC} be monotonic. Following power-up reset, a low-to-high clock transition must not occur until all applicable input and feedback setup times are met.



† This is the power-up reset time and applies to registered outputs only. The values shown are from characterization data.

‡ This is the setup time for input or feedback.

Figure 2. Power-Up Reset Waveforms

f_{max} SPECIFICATIONS

f_{max} without feedback, see Figure 3

In this mode, data is presented at the input to the flip-flop and clocked through to the Q output with no feedback. Under this condition, the clock period is limited by the sum of the data setup time and the data hold time (t_{su} + t_h). However, the minimum f_{max} is determined by the minimum clock period (t_w high + t_w low).

$$\text{Thus, } f_{\text{max}} \text{ without feedback} = \frac{1}{(t_{w\text{high}} + t_{w\text{low}})} \text{ or } \frac{1}{(t_{\text{su}} + t_{\text{h}})}$$

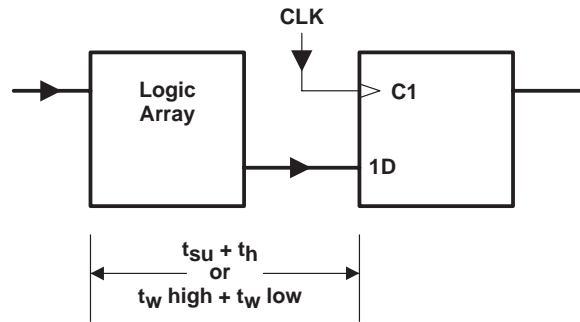


Figure 3. f_{max} Without Feedback

f_{max} with internal feedback, see Figure 4

This configuration is most popular in counters and on-chip state-machine designs. The flip-flop inputs are defined by the device inputs and flip-flop outputs. Under this condition, the period is limited by the internal delay from the flip-flop outputs through the internal feedback and logic array to the inputs of the next flip-flop.

$$\text{Thus, } f_{\text{max}} \text{ with internal feedback} = \frac{1}{(t_{\text{su}} + t_{\text{pd CLK-to-FB}})}$$

Where t_{pd} CLK-to-FB is the deduced value of the delay from CLK to the input of the logic array.

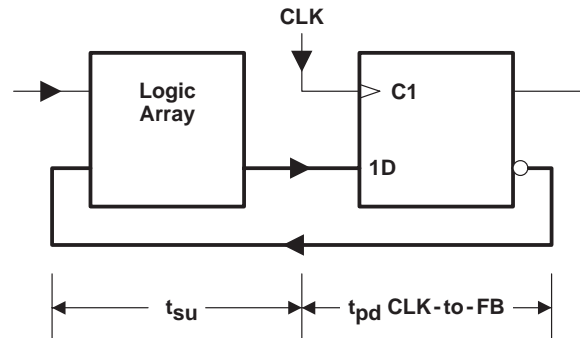


Figure 4. f_{max} With Internal Feedback

f_{max} SPECIFICATIONS

f_{max} with external feedback, see Figure 5

This configuration is a typical state-machine design with feedback signals sent off-chip. This external feedback could go back to the device inputs or to a second device in a multi-chip state machine. The slowest path defining the period is the sum of the clock-to-output time and the input setup time for the external signals ($t_{su} + t_{pd \text{ CLK-to-Q}}$).

$$\text{Thus, } f_{\text{max}} \text{ with external feedback} = \frac{1}{(t_{\text{su}} + t_{\text{pd CLK-to-Q}})}$$

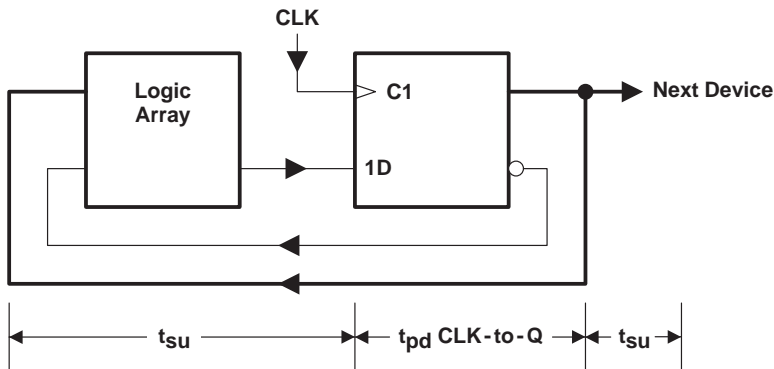


Figure 5. f_{max} With External Feedback

THERMAL INFORMATION

thermal management of the TIBPAL20R8-5C

Thermal management of the TIBPAL20R8-5CNT and TIBPAL20R8-5CFN is necessary when operating at certain conditions of frequency, output loading, and outputs switching simultaneously. The device and system application will determine the appropriate level of management.

Determining the level of thermal management is based on factors such as power dissipation (P_D), ambient temperature (T_A), and transverse airflow (FPM). Figures 6 (a) and 6 (b) show the relationship between ambient temperature and transverse airflow at given power dissipation levels. The required transverse airflow can be determined at a particular ambient temperature and device power dissipation level in order to ensure the device specifications.

Figure 7 illustrates how power dissipation varies as a function of frequency and the number of outputs switching simultaneously. It should be noted that all outputs are fully loaded ($C_L = 50$ pF). Since the condition of eight fully loaded outputs represents the worst-case condition, each application must be evaluated accordingly.

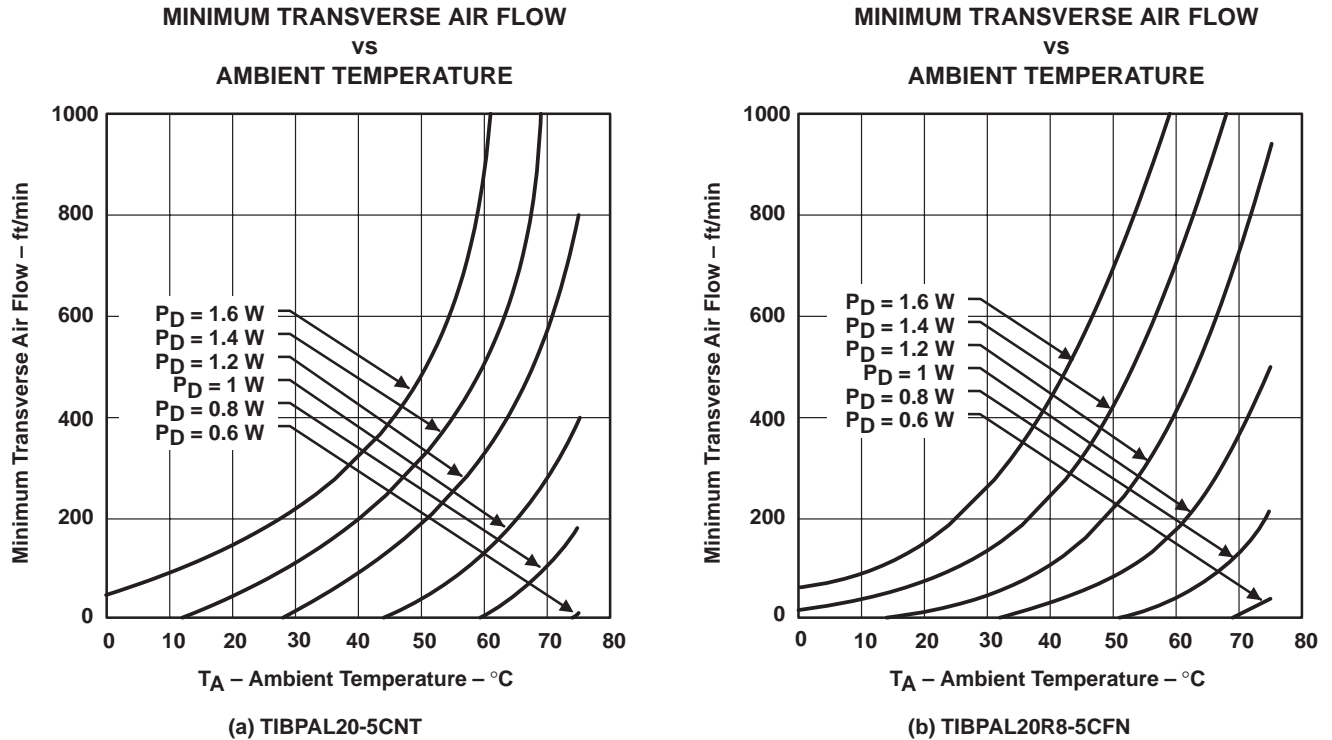


Figure 6

THERMAL INFORMATION

**POWER DISSIPATION
 vs
 FREQUENCY**

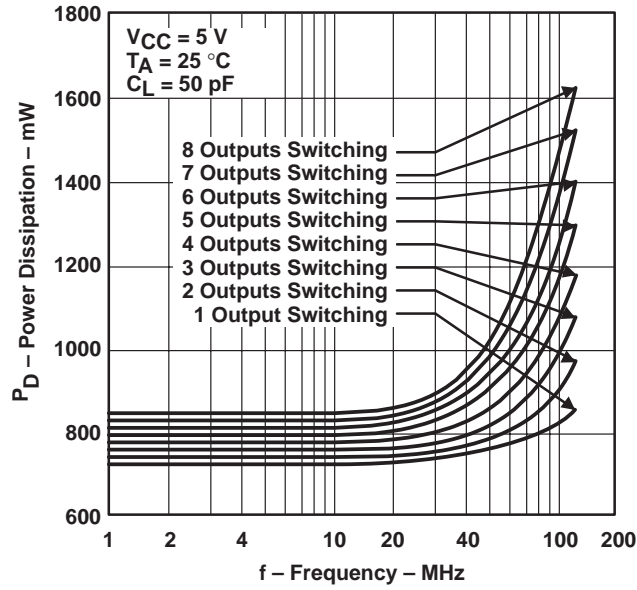
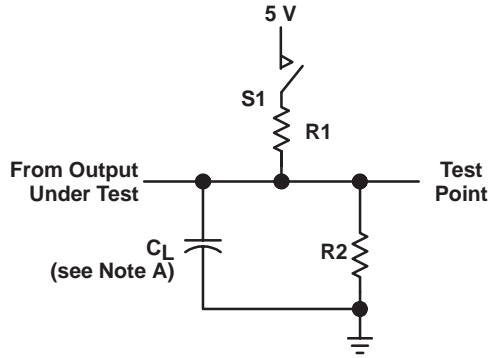
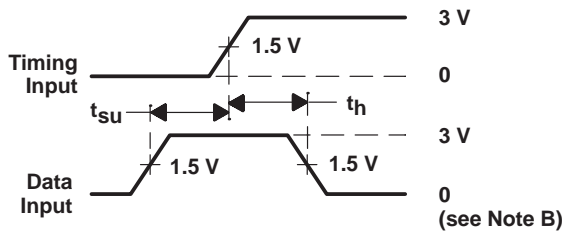


Figure 7

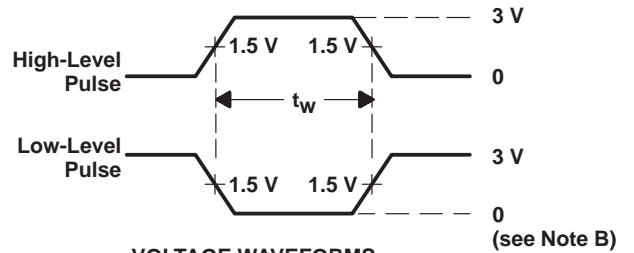
PARAMETER MEASUREMENT INFORMATION



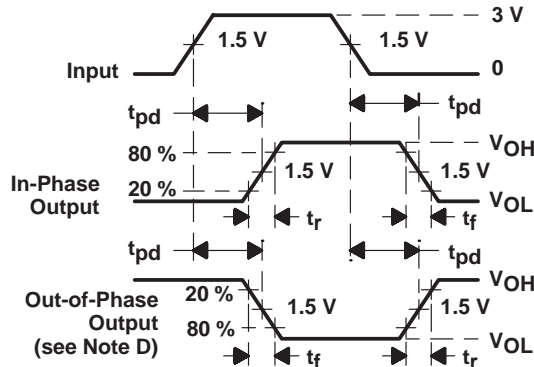
LOAD CIRCUIT FOR 3-STATE OUTPUTS



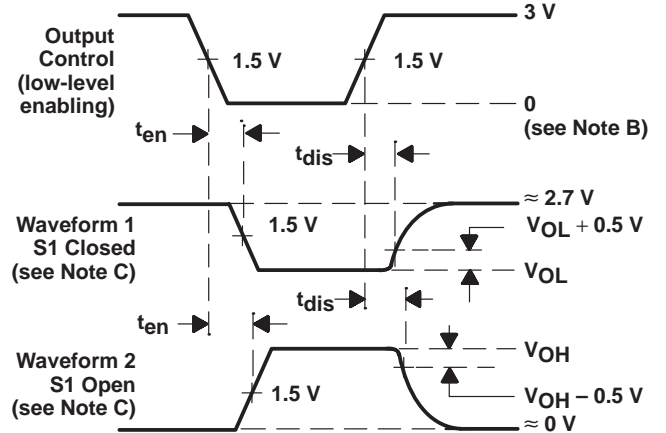
VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PULSE DURATIONS



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

- NOTES: A. C_L includes probe and jig capacitance and is 50 pF for t_{pd} and t_{en} , 5 pF for t_{dis} .
 B. All input pulses have the following characteristics: For C suffix, $PRR \leq 1$ MHz, $t_r = t_f = 2$ ns, duty cycle = 50%; For M suffix, $PRR \leq 10$ MHz, $t_r = t_f \leq 2$ ns, duty cycle = 50%.
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 D. When measuring propagation delay times of 3-state outputs, switch S1 is closed.
 E. Equivalent loads may be used for testing.

Figure 8. Load Circuit and Voltage Waveforms

metastable characteristics of TIBPAL20R4-5C, TIBPAL20R6-5C, and TIBPAL20R8-5C

At some point a system designer is faced with the problem of synchronizing two digital signals operating at two different frequencies. This problem is typically overcome by synchronizing one of the signals to the local clock through use of a flip-flop. However, this solution presents an awkward dilemma since the setup and hold time specifications associated with the flip-flop are sure to be violated. The metastable characteristics of the flip-flop can influence overall system reliability.

Whenever the setup and hold times of a flip-flop are violated, its output response becomes uncertain and is said to be in the metastable state if the output hangs up in the region between V_{IL} and V_{IH} . This metastable condition lasts until the flip-flop falls into one of its two stable states, which takes longer than the specified maximum propagation delay time (CLK to Q max).

From a system engineering standpoint, a designer cannot use the specified data sheet maximum for propagation delay time when using the flip-flop as a data synchronizer – how long to wait after the specified data sheet maximum must be known before using the data in order to guarantee reliable system operation.

The circuit shown in Figure 9 can be used to evaluate MTBF (Mean Time Between Failure) and Δt for a selected flip-flop. Whenever the Q output of the DUT is between 0.8 V and 2 V, the comparators are in opposite states. When the Q output of the DUT is higher than 2 V or lower than 0.8 V, the comparators are at the same logic level. The outputs of the two comparators are sampled a selected time (Δt) after SCLK. The exclusive OR gate detects the occurrence of a failure and increments the failure counter.

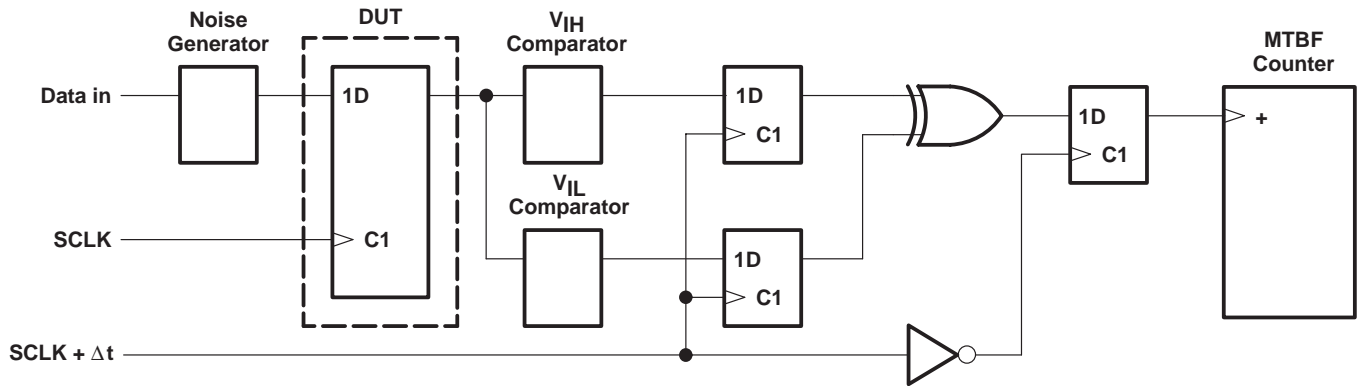


Figure 9. Metastable Evaluation Test Circuit

In order to maximize the possibility of forcing the DUT into a metastable state, the input data signal is applied so that it always violates the setup and hold time. This condition is illustrated in the timing diagram in Figure 10. Any other relationship of SCLK to data will provide less chance for the device to enter into the metastable state.

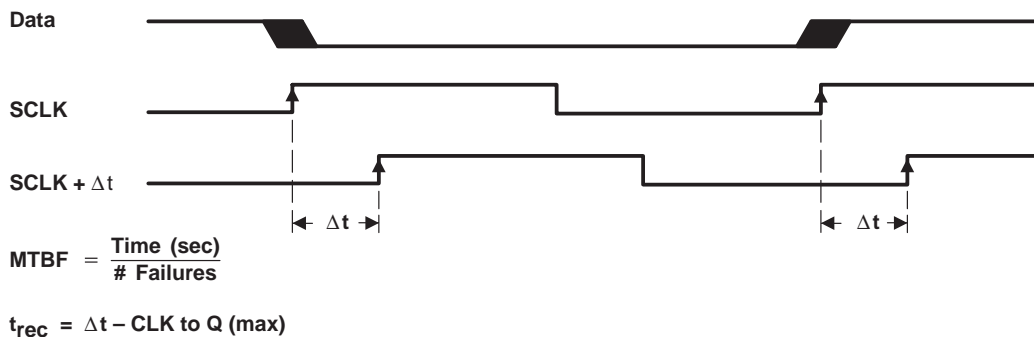


Figure 10. Timing Diagram

TIBPAL20R4-5C, TIBPAL20R6-5C, TIBPAL20R8-5C HIGH-PERFORMANCE *IMPACT-X*™ *PAL*® CIRCUITS

SRPS010F – D3353, OCTOBER 1989 – REVISED SEPTEMBER 1992

By using the described test circuit, MTBF can be determined for several different values of Δt (see Figure 9). Plotting this information on semilog scale demonstrates the metastable characteristics of the selected flip-flop. Figure 11 shows the results for the TIBPAL20'-5C operating at 1 MHz.

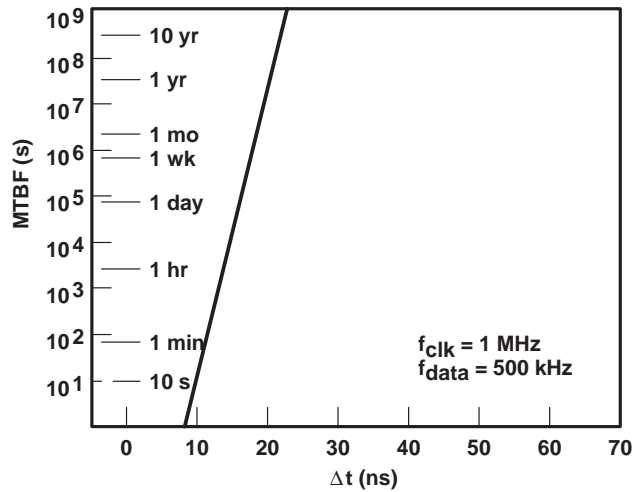


Figure 11. Metastable Characteristics

From the data taken in the above experiment, an equation can be derived for the metastable characteristics at other clock frequencies.

The metastable equation: $\frac{1}{\text{MTBF}} = f_{\text{SCLK}} \times f_{\text{data}} \times C1 \times e^{-C2 \times \Delta t}$

The constants C1 and C2 describe the metastable characteristics of the device. From the experimental data, these constants can be solved for: $C1 = 4.37 \times 10^{-3}$ and $C2 = 2.01$

Therefore

$$\frac{1}{\text{MTBF}} = f_{\text{SCLK}} \times f_{\text{data}} \times 4.37 \times 10^{-3} \times e^{-2.01 \times \Delta t}$$

definition of variables

DUT (Device Under Test): The DUT is a 5-ns registered PLD programmed with the equation $Q = D$.

MTBF (Mean Time Between Failures): The average time (s) between metastable occurrences that cause a violation of the device specifications.

f_{SCLK} (system clock frequency): Actual clock frequency for the DUT.

f_{data} (data frequency): Actual data frequency for a specified input to the DUT.

C1: Calculated constant that defines the magnitude of the curve.

C2: Calculated constant that defines the slope of the curve.

t_{rec} (metastability recovery time): Minimum time required to guarantee recovery from metastability, at a given MTBF failure rate. $t_{\text{rec}} = \Delta t - t_{\text{pd}}$ (CLK to Q, max)

Δt : The time difference (ns) from when the synchronizing flip-flop is clocked to when its output is sampled.

The test described above has shown the metastable characteristics of the TIBPAL20R4/R6/R8-5C series. For additional information on metastable characteristics of Texas Instruments logic circuits, please refer to TI Applications publication SDAA004, "Metastable Characteristics, Design Considerations for ALS, AS, and LS Circuits."



TYPICAL CHARACTERISTICS

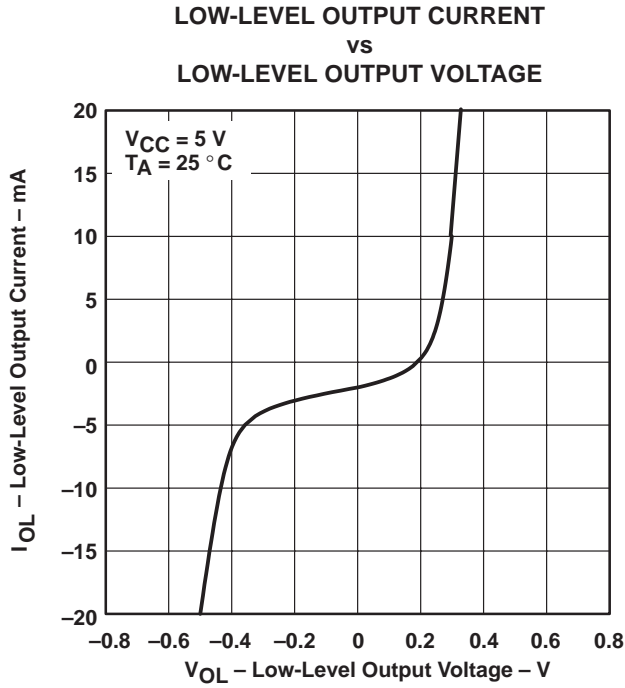


Figure 12

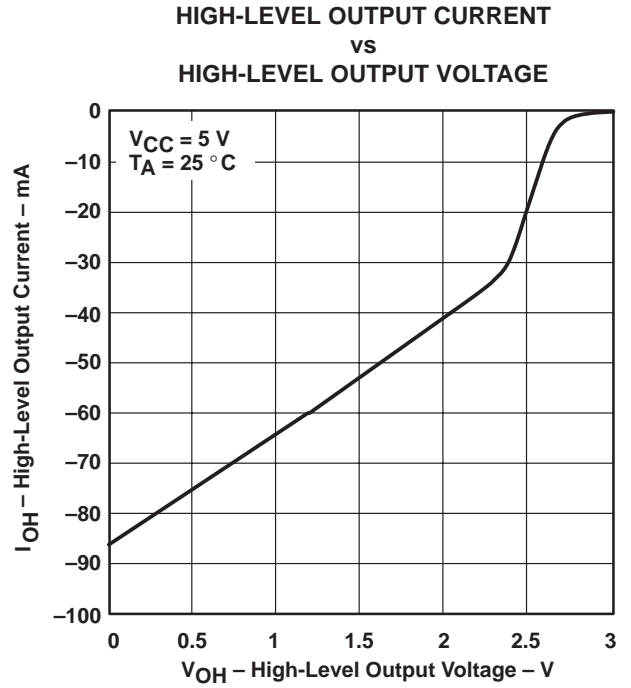


Figure 13

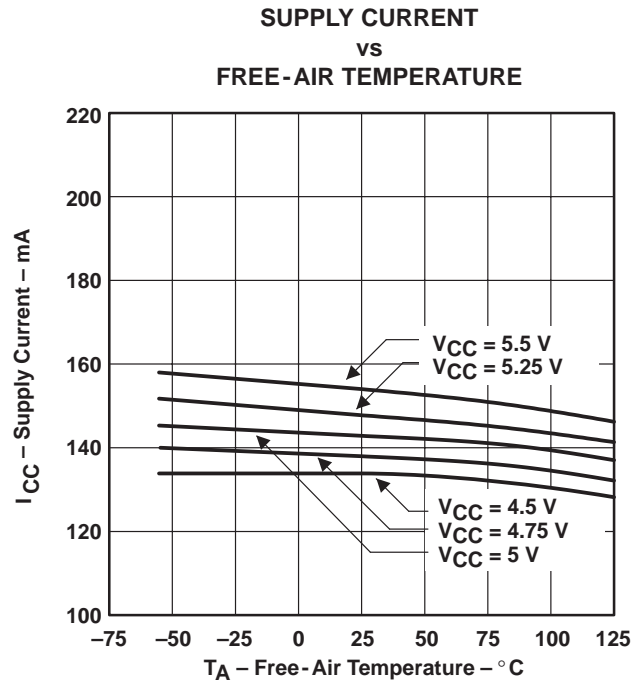


Figure 14

TYPICAL CHARACTERISTICS

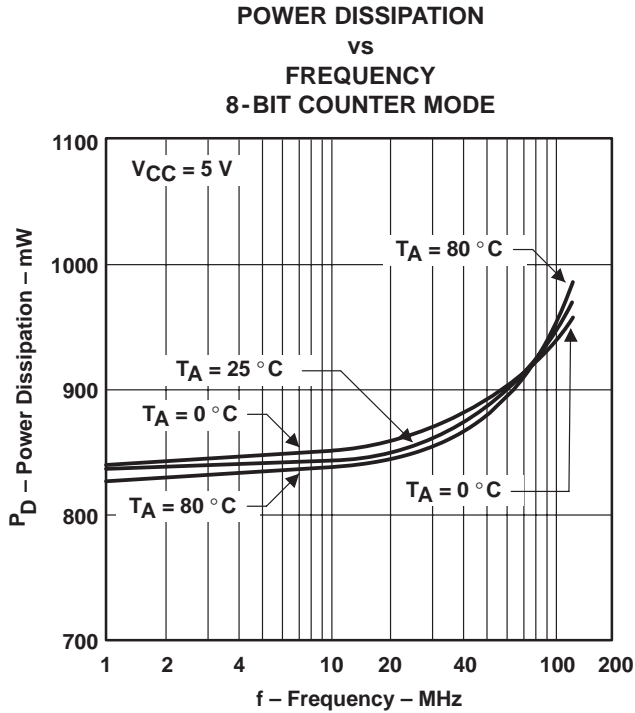


Figure 15

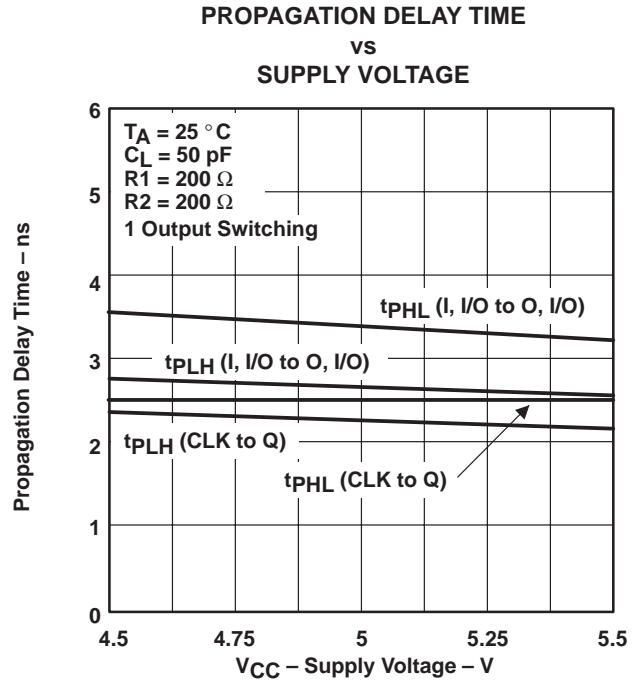


Figure 16

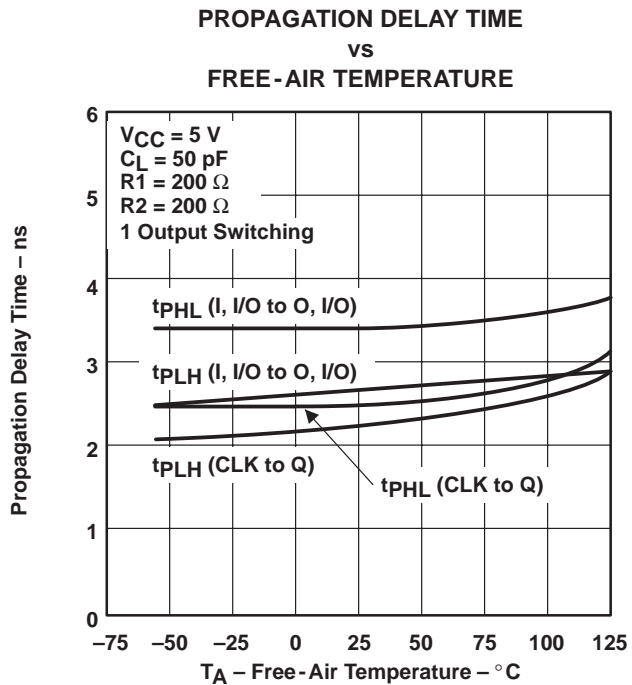


Figure 17

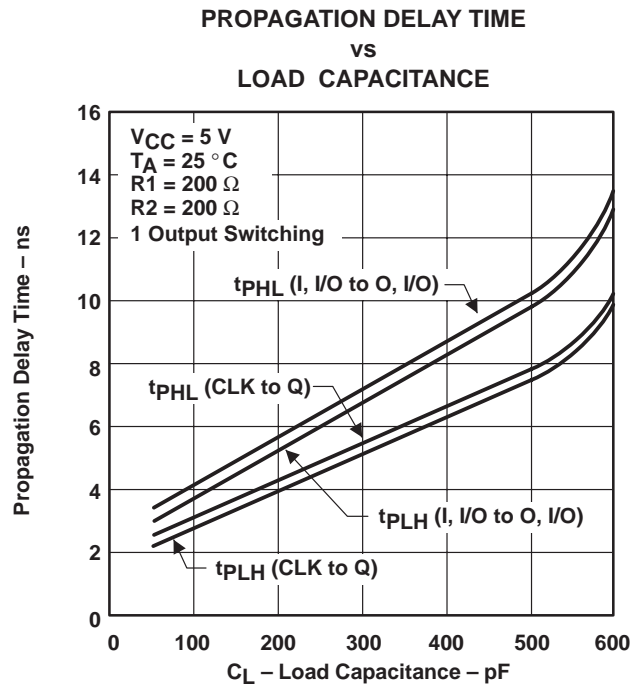


Figure 18

TYPICAL CHARACTERISTICS

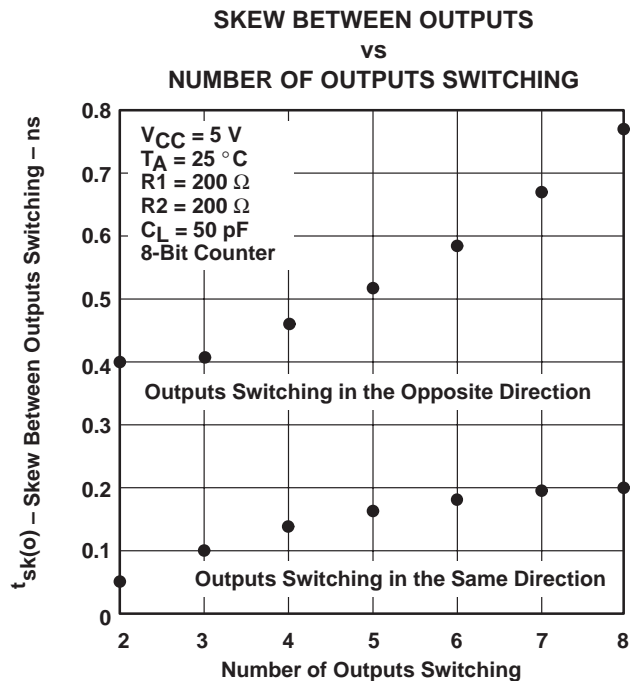


Figure 19

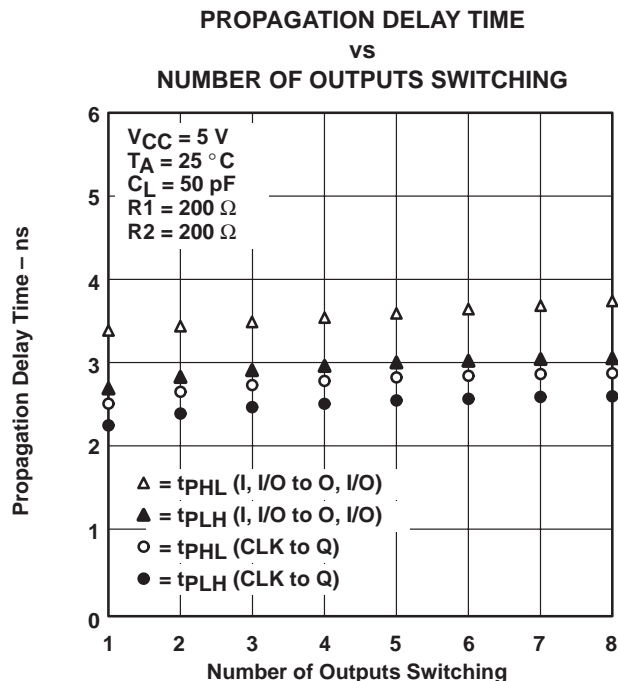


Figure 20

TI North American Sales Offices

ALABAMA: Huntsville: (205) 837-7530
ARIZONA: Phoenix: (602) 995-1007
CALIFORNIA: Irvine: (714) 660-1200
San Diego: (619) 278-9600
Santa Clara: (408) 980-9000
Woodland Hills: (818) 704-8100
COLORADO: Aurora: (303) 368-8000
CONNECTICUT: Wallingford: (203) 269-0074
FLORIDA: Altamonte Springs: (407) 260-2116
Fort Lauderdale: (305) 973-8502
Tampa: (813) 885-7588
GEORGIA: Norcross: (404) 662-7967
ILLINOIS: Arlington Heights: (708) 640-3000
INDIANA: Carmel: (317) 573-6400
Fort Wayne: (219) 489-4697
KANSAS: Overland Park: (913) 451-4511
MARYLAND: Columbia: (410) 964-2003
MASSACHUSETTS: Waltham: (617) 895-9100
MICHIGAN: Farmington Hills: (313) 553-1581
MINNESOTA: Eden Prairie: (612) 828-9300
MISSOURI: St. Louis: (314) 821-8400
NEW JERSEY: Iselin: (908) 750-1050
NEW MEXICO: Albuquerque: (505) 345-2555
NEW YORK: East Syracuse: (315) 463-9291
Fishkill: (914) 897-2900
Meville: (516) 454-6600
Pittsford: (716) 385-6770
NORTH CAROLINA: Charlotte: (704) 527-0930
Raleigh: (919) 876-2725
OHIO: Beachwood: (216) 765-7258
Beavercreek: (513) 427-6200
OREGON: Beaverton: (503) 643-6758
PENNSYLVANIA: Blue Bell: (215) 825-9500
PUERTO RICO: Hato Rey: (809) 753-8700
TEXAS: Austin: (512) 250-6769
Dallas: (214) 917-1264
Houston: (713) 778-6592
Midland: (915) 561-7137
UTAH: Salt Lake City: (801) 466-8972
WISCONSIN: Waukesha: (414) 798-1001
CANADA: Nepean: (613) 726-1970
Richmond Hill: (416) 884-9181
St. Laurent: (514) 335-8392

TI Regional Technology Centers

CALIFORNIA: Irvine: (714) 660-8140
Santa Clara: (408) 748-2222
GEORGIA: Norcross: (404) 662-7945
ILLINOIS: Arlington Heights: (708) 640-2909
INDIANA: Indianapolis: (317) 573-6400
MASSACHUSETTS: Waltham: (617) 895-9196
MEXICO: Mexico City: 491-70834
MINNESOTA: Minneapolis: (612) 828-9300
TEXAS: Dallas: (214) 917-3881
CANADA: Nepean: (613) 726-1970

Customer Response Center

TOLL FREE: (800) 336-5236
OUTSIDE USA: (214) 995-6611
(8:00 a.m. – 5:00 p.m. CST)

TI Authorized North American Distributors

Alliance Electronics, Inc. (military product only)
Almac/Arrow
Anthem Electronics
Arrow/Schweber
Future Electronics (Canada)
GRS Electronics Co., Inc.
Hall-Mark Electronics
Marshall Industries
Newark Electronics
Rochester Electronics, Inc.
(obsolete product only) (508) 462-9332
Wyle Laboratories
Zeus Components

TI Distributors

ALABAMA: Arrow/Schweber (205) 837-6955; Hall-Mark (205) 837-8700; Marshall (205) 881-9235.
ARIZONA: Anthem (602) 966-6600; Arrow/Schweber (602) 437-0750; Hall-Mark (602) 431-0030; Marshall (602) 496-0290; Wyle (602) 437-2088.
CALIFORNIA: Los Angeles/Orange County: Anthem (818) 775-1333, (714) 768-4444; Arrow/Schweber (818) 380-9686, (714) 838-5422; Hall-Mark (818) 773-4500, (714) 727-6000; Marshall (818) 878-7000, (714) 458-5301; Wyle (818) 880-9000, (714) 863-9953; Zeus (714) 921-9000, (818) 889-3838;
Sacramento: Anthem (916) 624-9744; Hall-Mark (916) 624-9781; Marshall (916) 635-9700; Wyle (916) 638-5282;
San Diego: Anthem (619) 453-9005; Arrow/Schweber (619) 565-4800; Hall-Mark (619) 268-1201; Marshall (619) 578-9600; Wyle (619) 565-9171; Zeus (619) 277-9681.
San Francisco Bay Area: Anthem (408) 453-1200; Arrow/Schweber (408) 441-9700, (510) 490-9477; Hall-Mark (408) 432-4000; Marshall (408) 942-4600; Wyle (408) 727-2500; Zeus (408) 629-4789.
COLORADO: Anthem (303) 790-4500; Arrow/Schweber (303) 799-0258; Hall-Mark (303) 790-1662; Marshall (303) 451-8383; Wyle (303) 457-9953.
CONNECTICUT: Anthem (203) 575-1575; Arrow/Schweber (203) 265-7741; Hall-Mark (203) 271-2844; Marshall (203) 265-3822.
FLORIDA: Fort Lauderdale: Arrow/Schweber (305) 429-8200; Hall-Mark (305) 971-9280; Marshall (305) 977-4880.
Orlando: Arrow/Schweber (407) 333-9300; Hall-Mark (407) 830-5855; Marshall (407) 767-8585; Zeus (407) 788-9100.
Tampa: Hall-Mark (813) 541-7440; Marshall (813) 573-1399.
GEORGIA: Arrow/Schweber (404) 497-1300; Hall-Mark (404) 623-4400; Marshall (404) 923-5750.
ILLINOIS: Anthem (708) 884-0200; Arrow/Schweber (708) 250-0500; Hall-Mark (312) 860-3800; Marshall (708) 490-0155; Newark (312) 784-5100.
INDIANA: Arrow/Schweber (317) 299-2071; Hall-Mark (317) 872-8875; Marshall (317) 297-0483.
IOWA: Arrow/Schweber (319) 395-7230.
KANSAS: Arrow/Schweber (913) 541-9542; Hall-Mark (913) 888-4747; Marshall (913) 492-3121.
MARYLAND: Anthem (301) 995-6640; Arrow/Schweber (301) 596-7800; Hall-Mark (301) 988-9800; Marshall (301) 622-1118; Zeus (301) 997-1118.
MASSACHUSETTS: Anthem (508) 657-5170; Arrow/Schweber (508) 658-0900; Hall-Mark (508) 667-0902; Marshall (508) 658-0810; Wyle (617) 272-7300; Zeus (617) 246-8200.



MICHIGAN: Detroit: Arrow/Schweber (313) 462-2290; Hall-Mark (313) 416-5800; Marshall (313) 525-5850; Newark (313) 967-0600.
MINNESOTA: Anthem (612) 944-5454; Arrow/Schweber (612) 941-5280; Hall-Mark (612) 881-2600; Marshall (612) 559-2211.
MISSOURI: Arrow/Schweber (314) 567-6888; Hall-Mark (314) 291-5350; Marshall (314) 291-4650.
NEW JERSEY: Anthem (201) 227-7960; Arrow/Schweber (201) 227-7880, (609) 596-8000; Hall-Mark (201) 515-3000, (609) 235-1900; Marshall (201) 882-0320, (609) 234-9100.
NEW MEXICO: Alliance (505) 292-3360.
NEW YORK: Long Island: Anthem (516) 864-6600; Arrow/Schweber (516) 231-1000; Hall-Mark (516) 737-0600; Marshall (516) 273-2424; Zeus (914) 937-7400.
Rochester: Arrow/Schweber (716) 427-0300; Hall-Mark (716) 425-3300; Marshall (716) 235-7620.
Syracuse: Marshall (607) 785-2345.
NORTH CAROLINA: Arrow/Schweber (919) 876-3132; Hall-Mark (919) 872-0712; Marshall (919) 878-9882.
OHIO: Cleveland: Arrow/Schweber (216) 248-3990; Hall-Mark (216) 349-4632; Marshall (216) 248-1788.
Columbus: Hall-Mark (614) 888-3313.
Dayton: Arrow/Schweber (513) 435-5563; Marshall (513) 898-4480; Zeus (513) 293-6162.
OKLAHOMA: Arrow/Schweber (918) 252-7537; Hall-Mark (918) 254-6110.
OREGON: Almac/Arrow (503) 629-8090; Anthem (503) 643-1114; Marshall (503) 644-5050; Wyle (503) 643-7900.
PENNSYLVANIA: Anthem (215) 443-5150; Arrow/Schweber (215) 928-1800; GRS (215) 922-7037; (609) 964-8560; Marshall (412) 788-0441.
TEXAS: Austin: Arrow/Schweber (512) 835-4180; Hall-Mark (512) 258-8848; Marshall (512) 837-1991; Wyle (512) 345-8853;
Dallas: Anthem (214) 238-7100; Arrow/Schweber (214) 380-6464; Hall-Mark (214) 553-4300; Marshall (214) 233-5200; Wyle (214) 235-9953; Zeus (214) 783-7010;
Houston: Arrow/Schweber (713) 530-4700; Hall-Mark (713) 781-6100; Marshall (713) 467-1666; Wyle (713) 879-9953.
UTAH: Anthem (801) 973-8555; Arrow/Schweber (801) 973-6913; Marshall (801) 973-2288; Wyle (801) 974-9953.
WASHINGTON: Almac/Arrow (206) 643-9992; Anthem (206) 483-1700; Marshall (206) 486-5747; Wyle (206) 881-1150.
WISCONSIN: Arrow/Schweber (414) 792-0150; Hall-Mark (414) 797-7844; Marshall (414) 797-8400.
CANADA: Calgary: Future (403) 235-5325;
Edmonton: Future (403) 438-2858;
Montreal: Arrow/Schweber (514) 421-7411; Future (514) 694-7710; Marshall (514) 694-8142
Ottawa: Arrow/Schweber (613) 226-6903; Future (613) 820-8313.
Quebec: Future (418) 897-6666.
Toronto: Arrow/Schweber (416) 670-7769; Future (416) 612-9200; Marshall (416) 458-8046.
Vancouver: Arrow/Schweber (604) 421-2333; Future (604) 294-1166.

TI Die Processors

Chip Supply (407) 298-7100
Elmo Semiconductor (818) 768-7400
Minco Technology Labs (512) 834-2022

D0892

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87671193A	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
5962-8767119KA	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type
5962-8767119LA	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
TIBPAL20L8-5CFN	ACTIVE	PLCC	FN	28	37	TBD	CU SNPB	Level-1-220C-UNLIM
TIBPAL20L8-5CNT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TIBPAL20R4-5CFN	OBSOLETE	PLCC	FN	28		TBD	Call TI	Call TI
TIBPAL20R4-5CNT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
TIBPAL20R6-5CFN	ACTIVE	PLCC	FN	28	37	TBD	CU SNPB	Level-1-220C-UNLIM
TIBPAL20R6-5CNT	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TIBPAL20R8-5CFN	OBSOLETE	PLCC	FN	28		TBD	Call TI	Call TI
TIBPAL20R8-5CNT	OBSOLETE	PDIP	NT	24		TBD	Call TI	Call TI
TIBPAL20R8-7MFKB	ACTIVE	LCCC	FK	28	1	TBD	POST-PLATE	N / A for Pkg Type
TIBPAL20R8-7MJTB	ACTIVE	CDIP	JT	24	1	TBD	A42	N / A for Pkg Type
TIBPAL20R8-7MWB	ACTIVE	CFP	W	24	1	TBD	A42	N / A for Pkg Type

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

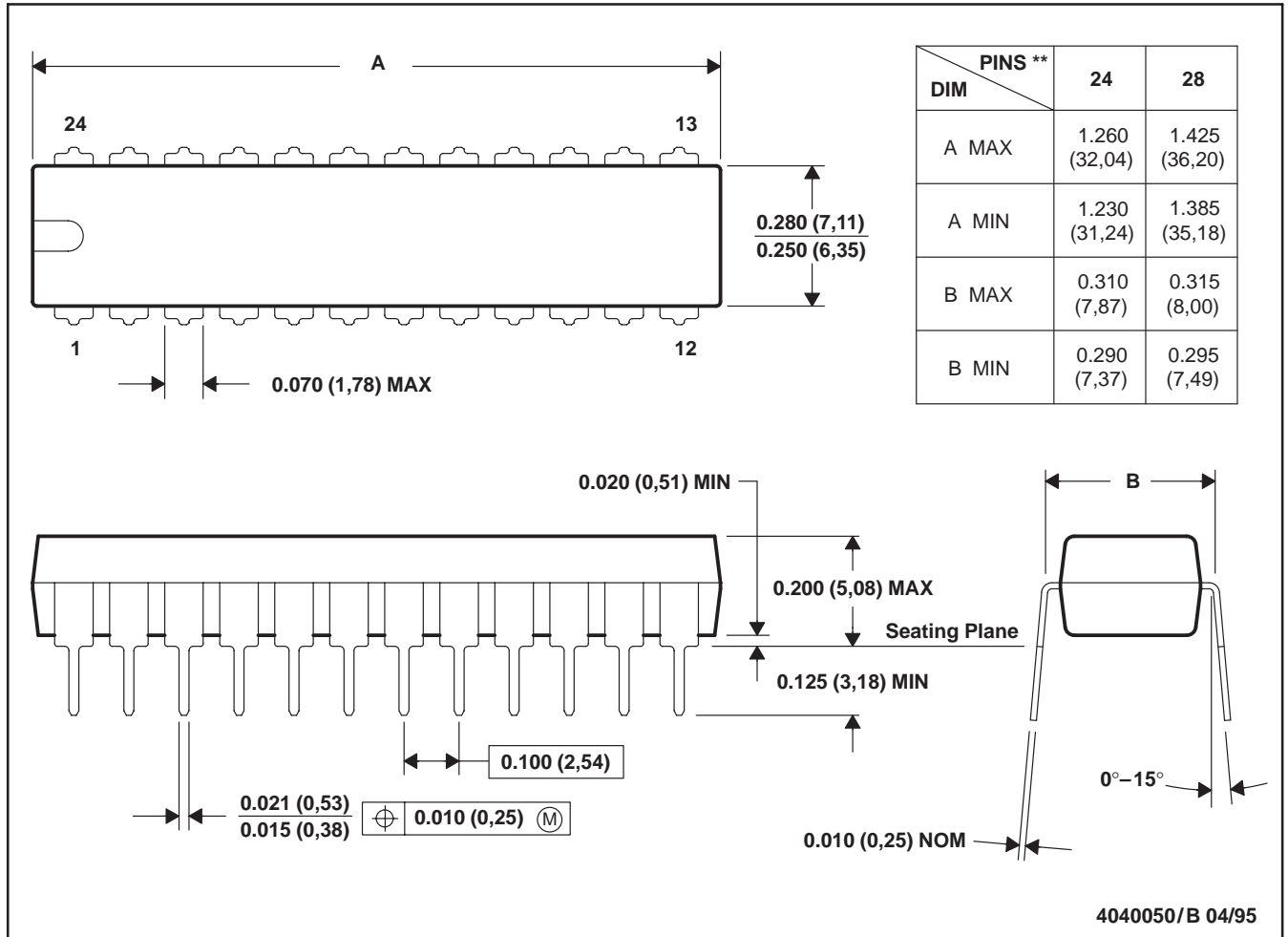


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

NT (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.

FN (S-PQCC-J**)

PLASTIC J-LEADED CHIP CARRIER

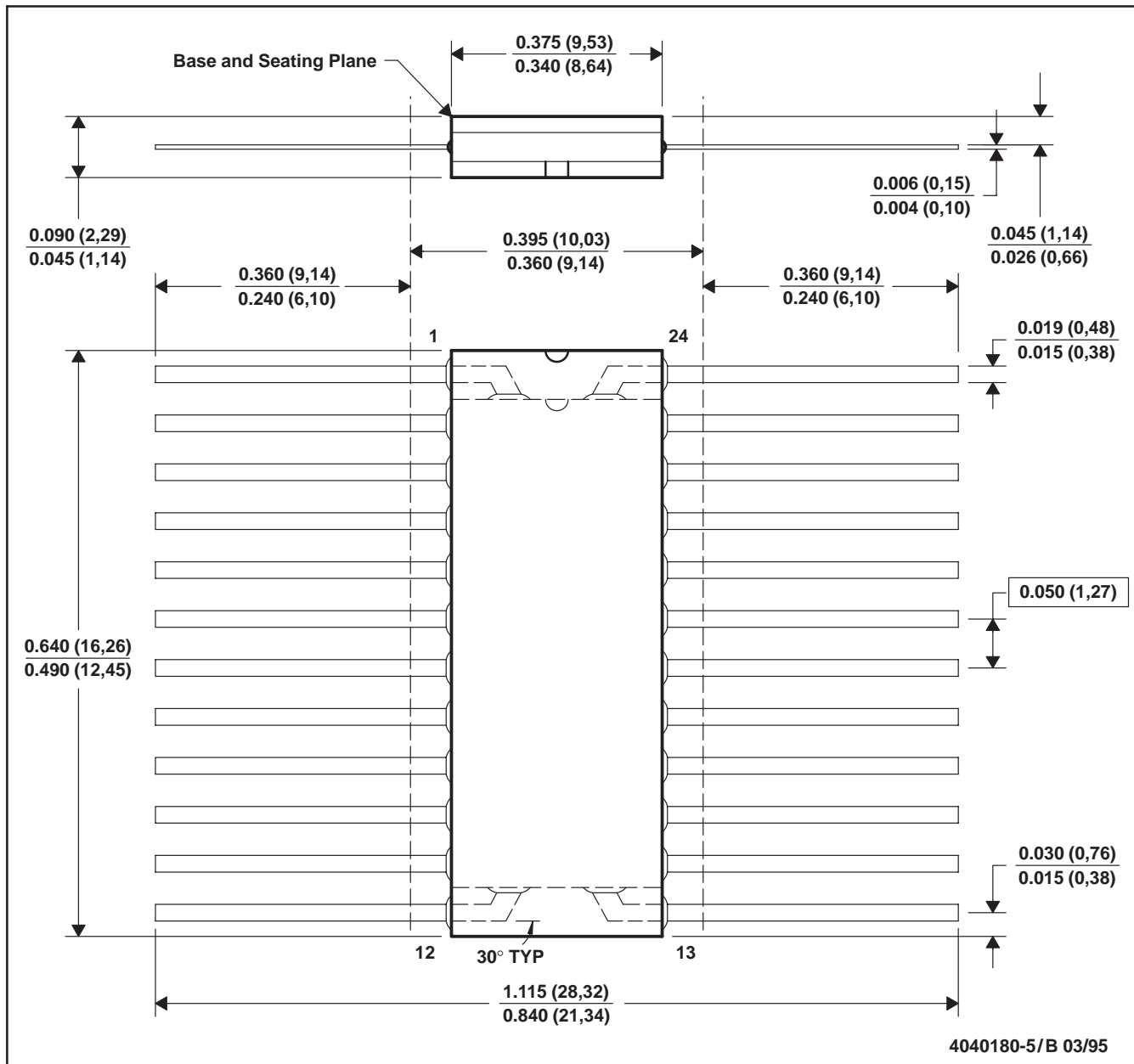
20 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-018

W (R-GDFP-F24)

CERAMIC DUAL FLATPACK

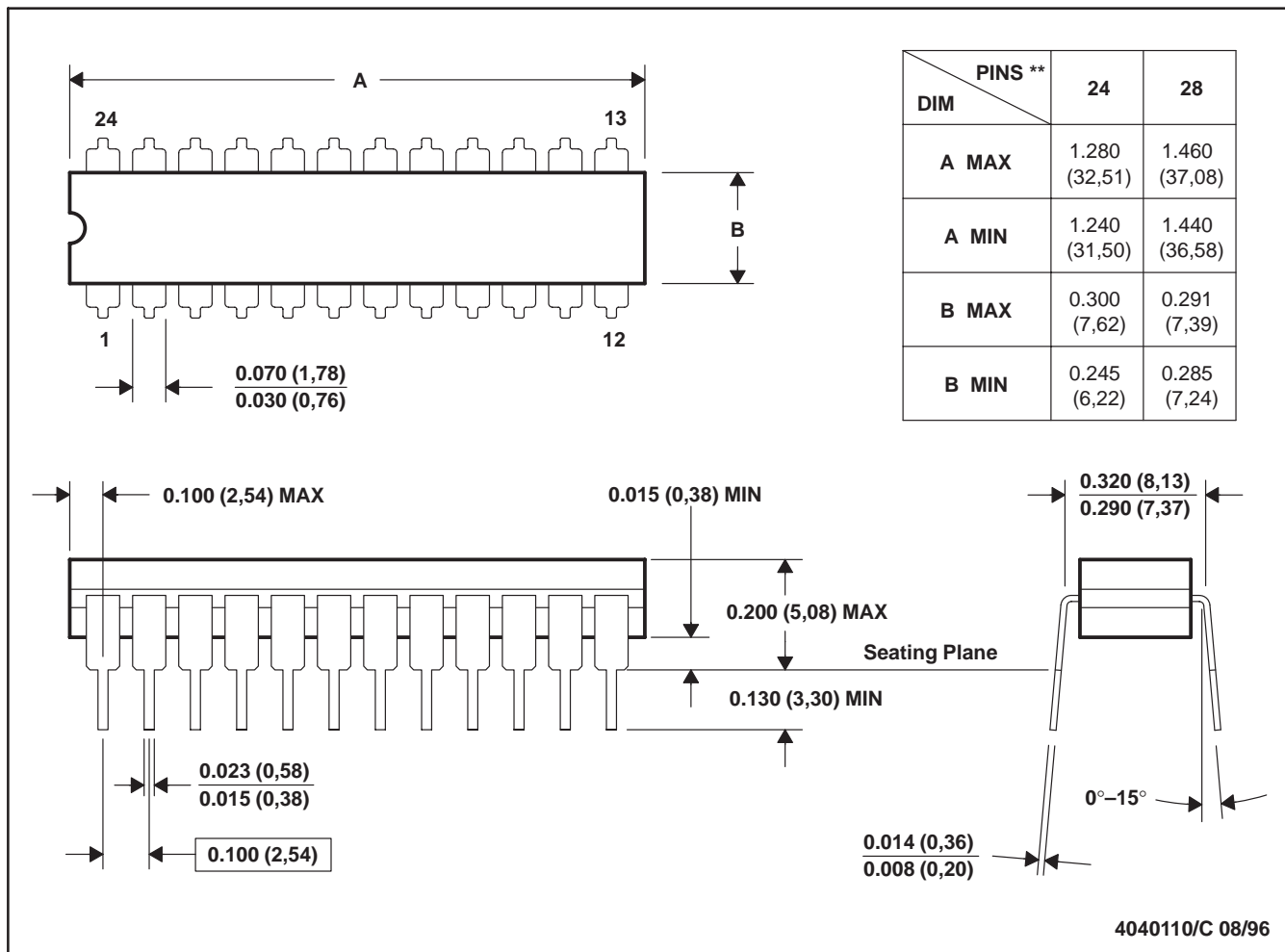


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Falls within MIL-STD-1835 GDFP2-F24 and JEDEC MO-070AD
 - E. Index point is provided on cap for terminal identification only.

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE

24 LEADS SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification.
 E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
RF/IF and ZigBee® Solutions	www.ti.com/lprf

Applications

Audio	www.ti.com/audio
Automotive	www.ti.com/automotive
Broadband	www.ti.com/broadband
Digital Control	www.ti.com/digitalcontrol
Medical	www.ti.com/medical
Military	www.ti.com/military
Optical Networking	www.ti.com/opticalnetwork
Security	www.ti.com/security
Telephony	www.ti.com/telephony
Video & Imaging	www.ti.com/video
Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2008, Texas Instruments Incorporated